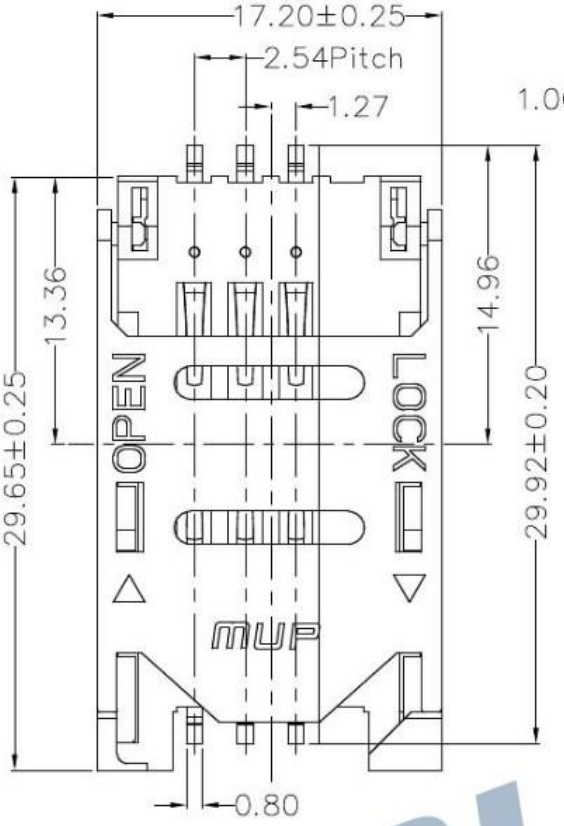
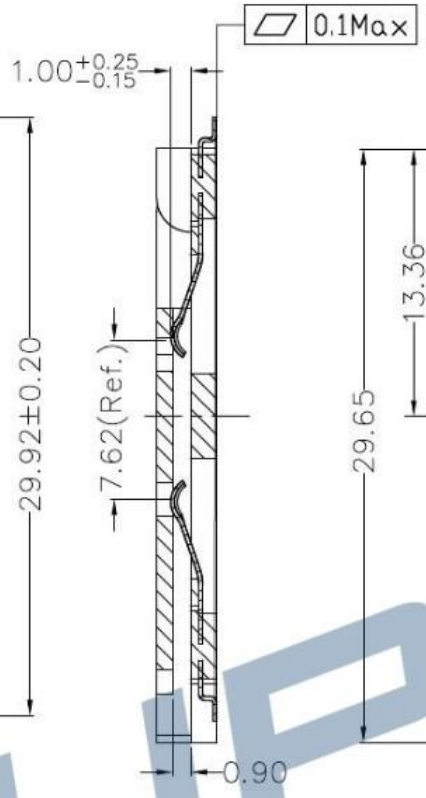
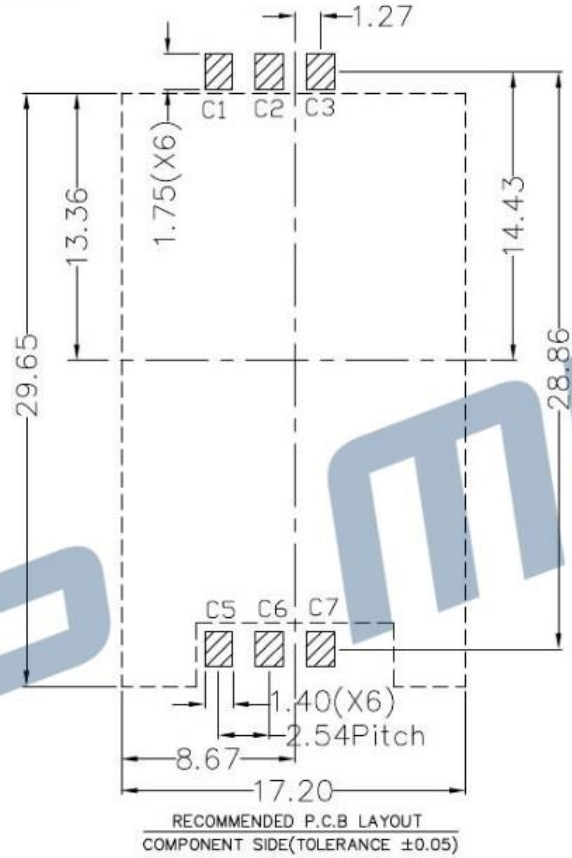
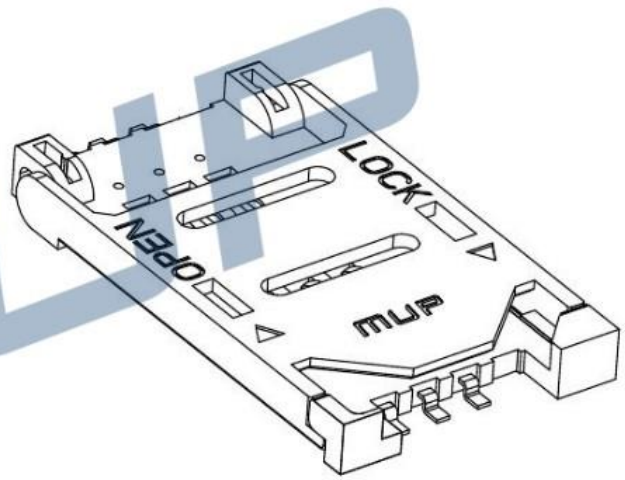
| REV. | DESCRIPTION OF REVISIONS | APPR. | DRAW. | RELEASE | DATE |
|---|---|---|---|---|---|
| X1 | | | | | |
| X2 | | | | | |

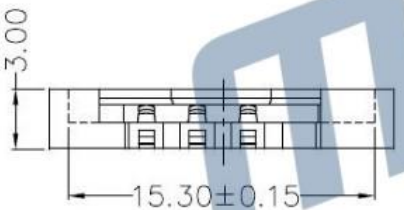



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)




TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 29.65LX17.20WX3.00H mm

Weight: Approx 1.30±0.2g

Durability: 5,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical,100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C,30sec.Max

IR reflow: 250°C,5sec.Max

Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics

Operating temperature: −40°C~+85°C

Operating humidity: 10%~+95%RH

| ITEM | PART NAME | Q'TY | MATERIAL | FINISH |
|---|---|---|---|---|
| 1 | BASE | 1 | Hi−temp Thermoplastic | Black UL94V−0 |
| 2 | COVER | 1 | Hi−temp Thermoplastic | Black UL94V−0 |
| 3 | DATA CONTACT | 6 | Copper Alloy | Contact area:Gold plated |

Unless otherwise specified, other tolerance are:

| | | | |
|---|---|---|---|
| X ±0.35 | X° ±5° | | |
| X.X ±0.25 | X.X° ±4° | | |
| X.XX ±0.15 | X.XX° ±3° | | |
| X.XXX ±0.10 | X.XXX° ±2° | | |

MUP® MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**

MODEL NO: **MUP C712-1**

TYPE : **H3.0 without post 6p**

| PROJ. | UNIT | SCALE |
|---|---|---|
| | mm | 1:1 |

CUSTOMER DRAWING

| | | |
|---|---|---|
| DRAWN | Zoey | Mar.10.2006 |
| CHECKED | Jimmy | Mar.10.2006 |
| APPROVAL | Simon | Mar.10.2006 |

DWG NO.: DWG−MUP−C712−001

SHEET 1/1

REVISION X1

MUP MUP